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Product Change Notification - JAON-17JDSD193 (Printer Friendly)

Date: 09 Jun 2016

Product Analog (Thermal, Power Management & Safety)

Category:

Notification subject: CCB 2596 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 40K wafer technology available in 8L MSOP package at MTAI assembly site

Notification text: **PCN Status:**
Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 40K wafer technology available in 8L MSOP package at MTAI assembly site.

Pre Change:

Gold (Au) bond wire

Post Change:

Palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MTAI assembly site	MTAI assembly site

Wire material	Au wire	CuPdAu wire
Die attach material	8390A	8390A
Molding compound material	G600	G600
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:

None

Reason for Change:

To improve manufacturability and qualify palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

Summary Table:

	June 2016				
	22	23	24	25	26
WW					
Initial PCN Issue Date		X			
Qual Report Availability			X		
Final PCN Issue Date			X		
Estimated Implementation Date					X

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:

June 9, 2016: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_JAON-17JDSD193_Qual_Plan.pdf](#)
[PCN_JAON-17JDSD193_Affected_CPN.pdf](#)
[PCN_JAON-17JDSD193_Affected_CPN.xls](#)

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